



Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-17 (Canceled)

Claim 18 (Currently amended): A method of electrically connecting an electronic device to a substrate, said method comprising:

passing free ends of a plurality of elongate spring contacts attached to said electronic device through into openings in a plurality of conductive recesses at a surface of in said substrate, each said recess comprising a bottom portion disposed within said substrate that prevents said free ends from passing through said substrate; and

applying a force to said electronic device and thereby pressing said free ends against said bottom portions of said conductive recesses located within said substrate, wherein electrical connections between said elongate spring contacts and said conductive recesses are established and maintained substantially entirely due to said pressing.

Claim 19 (Previously presented): The method of claim 18, wherein said electronic device comprises a semiconductor device.

Claim 20 (Previously presented): The method of claim 18, wherein each of said recesses is V shaped.

Claim 21 (Previously presented): The method of claim 18, wherein each of said recesses is U shaped.

Claim 22 (Previously presented): The method of claim 18, wherein each of said recesses is trapezoidal shaped.

Claim 23 (New): The method of claim 18, wherein each of said recesses is wider near a surface of said substrate than within said substrate.

Claim 24 (New): The method of claim 18, wherein each of said recesses extends into said substrate and is tapered inwardly.

Claim 25 (New): The method of claim 18 further comprising removing said force, wherein said electrical connections are substantially eliminated.